



## Product Change Notification: MFOL-25BUUV104

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### Date:

05-Jun-2025

### Product Category:

High Voltage Power Modules

### Notification Subject:

CCB 7593 Final Notice: Implement new protective packing material changes (Rivet) for selected MSCSMxx, CMCOSxx, CMGESxx, APTM1xx, APTGFxx, CMFIGxx, CMANGxx, MSCGLxx, APTGTxx, APTGLxx, CMTFGxx, CMAOGxx, CMPWGxx, CMGIGxx, CMCLGxx, APTGXxx, CMBBGxx, APTM2xx, APTM5xx, CMTTMxx, CMHIMxx, CMARMxx, APTGRxx, MSCM1xx, CMKLMxx, CMBAMxx, CMAOMxx, and APTC6xx device families available in Module package at MP3B assembly site.

### Affected CPNs:

[MFOL-25BUUV104\\_Affected\\_CPN\\_06052025.pdf](#)

[MFOL-25BUUV104\\_Affected\\_CPN\\_06052025.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Implement new protective packing material changes (Rivet) for selected MSCSMxx, CMCOSxx, CMGESxx, APTM1xx, APTGFxx, CMFIGxx, CMANGxx, MSCGLxx, APTGTxx, APTGLxx, CMTFGxx, CMAOGxx, CMPWGxx, CMGIGxx, CMCLGxx, APTGXxx, CMBBGxx, APTM2xx, APTM5xx, CMTTMxx, CMHIMxx, CMARMxx, APTGRxx, MSCM1xx, CMKLMxx, CMBAMxx, CMAOMxx, and APTC6xx device families available in Module package at MP3B assembly site.

### Pre and Post Summary Changes:

|  | Pre Change | Post Change |
|--|------------|-------------|
|--|------------|-------------|

|                                |                                                 |                                            |
|--------------------------------|-------------------------------------------------|--------------------------------------------|
| <b>Assembly Site</b>           | Microchip Technology Inc. (MPHIL-3) (MP3B)      | Microchip Technology Inc. (MPHIL-3) (MP3B) |
| <b>Packing Material/Method</b> | See Pre and Post change summary for comparison. |                                            |

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve productivity by implementing new protective packing material changes (Rivet).

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 08 July 2025 (date code: 2528)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

|                                      | <b>June 2025</b> |    |    |    | <b>July 2025</b> |    |    |    |    |
|--------------------------------------|------------------|----|----|----|------------------|----|----|----|----|
| <b>Work Week</b>                     | 23               | 24 | 25 | 26 | 27               | 28 | 29 | 30 | 31 |
| <b>Qual Report Availability</b>      | X                |    |    |    |                  |    |    |    |    |
| <b>Final PCN Issue Date</b>          | X                |    |    |    |                  |    |    |    |    |
| <b>Estimated Implementation Date</b> |                  |    |    |    |                  | X  |    |    |    |

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** June 05, 2025: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

## **Attachments:**

**PCN\_MFOL-25BUUV104\_Pre and Post Change Summary.pdf**

**PCN\_MFOL-25BUUV104 Qualification Report.pdf**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

CMAOGLQ300A120G

APTGT400DU120G

APTGL475U120DAG

APTGT400A120G

APTGL240TL120G

CMPWGT300V60G

APTGT300DA170G

APTGT300DA60G

CMGIGLQ300H65G

APTGT300DA120G

APTGT300H60G

APTGT300DU60G

APTGT300SK170G

CMCLGT600DA60G

APTGT225DU170G

APTGT200TL60G

APTGT450A60G

APTGT300A170G

APTGT300A120G

APTGT400TL65G

APTGT400U170DAG

APTGLQ200H65G

APTGLQ150H120G

APTGLQ300SK120G

APTGLQ300A120G

APTGT300TL65G

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APTGT300TL60G

APTGX600A120T6G

APTGX600A170T6G

APTGX200H120G

APTGX600DU120T6G

APTGX450A120T6G

APTGX450DU120T6G

APTGX300TL120G

APTGX300H120G

APTGX300H170G

APTGX600DA120T6G

APTGX600DA170T6G

APTGX600DU170T6G

APTGX600SK120T6G

APTGX600SK170T6G

APTGX300DU120T6G

APTGX300DU170T6G

APTGX300A170T6G

APTGX300HR120G

APTGX300HR170G

APTGX300A120T6G

MSCSM120AM13CT6AG

CMBBGLQ400A120CG

APTGLQ400A120CT6AG

APTM20SKM04G

APTM100A13DG

APTM100A13SG

APTM50DAM19G

CMTTM100UM65SAG

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APTM50AM24SG

APTM120DU15G

APTM20AM06SG

APTM120UM70DAG

CMHIM100UM65SAG

APTM100UM65SAG

APTM100UM45DAG

CMARM20DUM04G-AS

APTM20DAM04G

APTM20DAM05G

APTGR300SK120G

MSCM10AU40AG

APTM20AM02FG

CMKLM10AU40AG

APTM100A13SCG

APTM100AM90FG

APTM100H18FG

APTM20UM03FAG

APTM50HM38FG

APTM50AM17FG

APTM120H29FG

APTM20AM04FG

CMBAM20DUM04FG

APTM100UM45FAG

APTM20HM08FG

APTM20HM10FG

APTM50AM17FAG

CMAOM20HM08FG

APTC60AM18SCG

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MSCSM120HRM08NG  
CMCOSM120DUM027TAMG-AS  
MSCSM170HRM11NG  
MSCSM170HRM075NG  
MSCSM120HRM052NMG  
MSCSM120VR1M11CT6AG  
MSCSM120VR1M062CT6AG  
MSCSM70VR1M03CT6AG  
MSCSM70VR1M07CT6AG  
MSCSM120DUM042AMG  
MSCSM120HM083AG  
MSCSM120HM063AG  
MSCSM120AM027T6AG  
MSCSM70HM038AG  
MSCSM70HM05AG  
MSCSM70AM025T6AG  
MSCSM120HRM052NG  
MSCSM70TLM05CAG  
MSCSM120TLM11CAG  
MSCSM170TLM11CAG  
MSCSM170TLM15CAG  
MSCSM120TLM08CAG  
MSCSM70TLM07CAG  
MSCSM330AM27CAG  
MSCSM120DUM042AG  
MSCSM120DUM027AG  
MSCSM170DUM039AG  
MSCSM170DUM058AG  
MSCSM70DUM025AG

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MSCSM170HM12CAG

MSCSM170HM087CAG

MSCSM70DUM017AG

MSCSM120AM042CT6AG

MSCSM120AM027CT6AG

MSCSM70AM025CT6AG

MSCSM120AM042T6AG

MSCSM120UM036DCT6AG

CMGESM120DUM027AG

MSCSM170AM058CT6AG

MSCSM170AM039CT6AG

MSCSM70HM038CAG

MSCSM120HM083CAG

MSCSM70HM05CAG

MSCSM120HM063CAG

APTM10UM01FT6AG

APTM10UM01FAG

APTM10HM05FG

APTM10AM02FG

APTGF150A120DG

CMFIGF100V120G

APTGF300A120G

APTGF200SK120G

CMANGF75H120G

APTGF300SK120G

APTGF300U120DG

APTGF150H120G

APTGF150DH120G

MSCGLQ200A120DG

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APTGT200A120G

APTGLQ400A120T6G

APTGLQ225H65G

APTGLQ300H65G

APTGLQ200H120G

CMTFGLQ400A120T6G-AS

APTGT600SK60G

APTGL875U120DAG

APTGT150SK120G

APTGT150DU120G

APTGT600DU60G

APTGT600A60G

APTGLQ600A65T6G

APTGT200DU120G

APTGT200DH120G